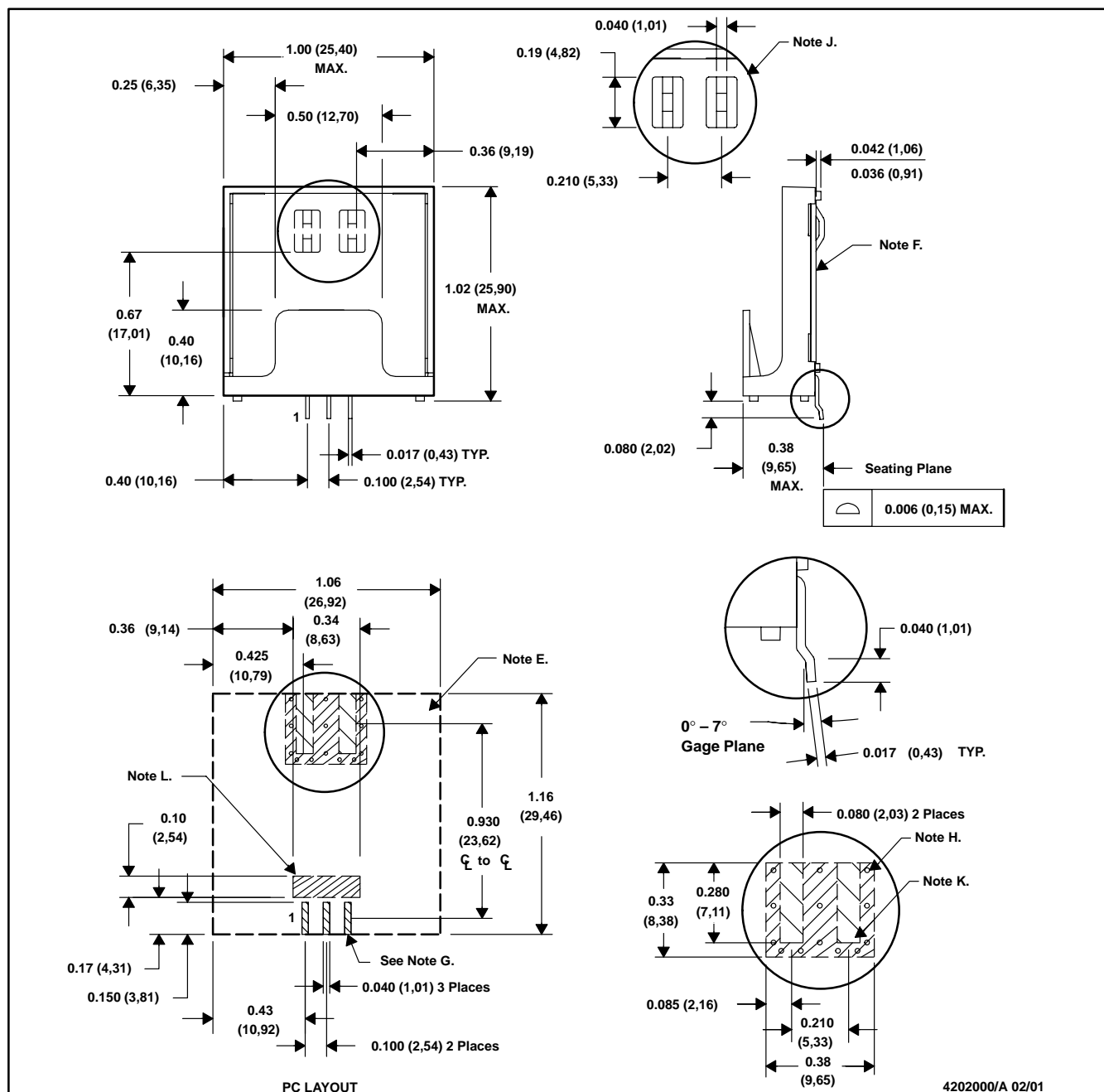


EAL (R-PSIP-G3)

PLASTIC SINGLE-IN-LINE MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2-place decimals are ± 0.030 (± 0.76 mm).
 - D. 3-place decimals are ± 0.010 (± 0.25 mm).
 - E. Recommended mechanical keep-out area.
 - F. The metal tab is isolated but electrically conductive. No signal traces are allowed under the metal tab area. A solid copper island is recommended, which may be grounded.
 - G. Power pin connections should utilize two or more vias per input, ground and output pin.

- H. Minimum copper land area required for solder tab. Vias are recommended to improve copper adhesion or connect land to other ground area.
- J. Underside solder tabs detail
- K. Solder mask openings to copper island for solder joints to mechanical pins.
- L. No copper, power or signal traces in this area.

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